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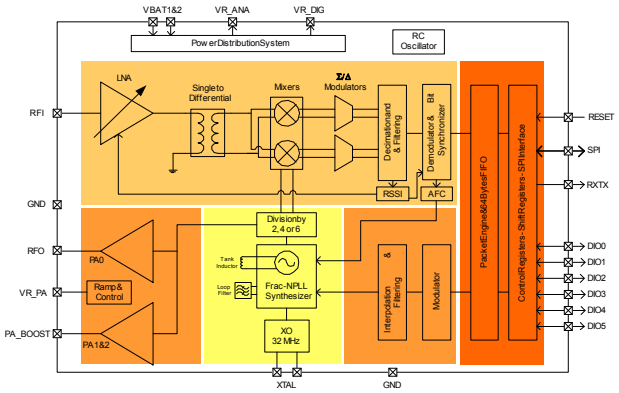
SX1232 - 868 & 915MHz Ultra Low Power High Link Budget Integrated UHF Transceiver



GENERAL DESCRIPTION

The SX1232 is a fully integrated ISM band transceiver optimized for use in the (EN 300 220-1) 868 MHz band in Europe and the (FCC Part 15) 915 MHz band in the US with a minimum of external components. It offers a combination of high link budget and low current consumption in all operating modes. The 143 dB link budget is achieved by a low noise CMOS receiver front end and up to +20 dBm of transmit output power. A pair of internal power amplifiers are provided permitting either fully regulated - for constant RF performance, or direct supply connection - for optimal efficiency. This makes SX1232 ideal for either M2M applications powered by alkaline battery chemistries or long battery life metering applications using Lithium battery chemistries.

The Low-IF architecture of the SX1232 sees fast transceiver start times and demodulation predicated towards low modulation index and gaussian filtered spectrally efficient modulation formats.

APPLICATIONS

- Automated Meter Reading
- Wireless Sensor Networks
- Home and Building Automation
- Wireless Alarm and Security Systems
- Industrial Monitoring and Control

KEY PRODUCT FEATURES

- +20 dBm - 100 mW Constant RF output vs. Vsupply
- +14 dBm high efficiency PA
- Programmable bit rate up to 300kbps
- High Sensitivity: down to -123 dBm at 1.2 kbps
- Bullet-proof front end: IIP3 = -12 dBm
- 80 dB Blocking Immunity
- Low RX current of 9.3 mA, 100nA register retention
- Fully integrated synthesizer with a resolution of 61 Hz
- FSK, GFSK, MSK, GMSK and OOK modulations
- Built-in Bit Synchronizer performing Clock Recovery
- Sync Word Recognition
- Preamble detection
- io-homecontrol® features
- 115 dB+ Dynamic Range RSSI
- Automatic RF Sense with ultra-fast AFC
- Packet engine up to 255 bytes with CRC
- Built-in temperature sensor and Low Battery indicator

ORDERING INFORMATION

Part Number	Delivery	MOQ / Multiple
SX1232IMLTRT	Tape & Reel	3000 pieces
SX1232BIMLTRT	Tape & Reel	3000 pieces

- QFN 24 Package - Operating Range [-40;+85°C]
- QFN28 Package - Operating Range [-40;+85°C]
- Pb-free, Halogen free, RoHS/WEEE compliant product

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Acronyms

BOM	Bill Of Materials
BR	Bit Rate
BW	Bandwidth
CCITT	Comité Consultatif International Téléphonique et Télégraphique - ITU
CRC	Cyclic Redundancy Check
DAC	Digital to Analog Converter
ETSI	European Telecommunications Standards Institute
FCC	Federal Communications Commission
Fdev	Frequency Deviation
FIFO	First In First Out
FIR	Finite Impulse Response
FS	Frequency Synthesizer
FSK	Frequency Shift Keying
GUI	Graphical User Interface
IC	Integrated Circuit
ID	IDentificator
IF	Intermediate Frequency
IRQ	Interrupt ReQuest
ITU	International Telecommunication Union
LFSR	Linear Feedback Shift Register
LNA	Low Noise Amplifier
LO	Local Oscillator
LSB	Least Significant Bit
MSB	Most Significant Bit
NRZ	Non Return to Zero
OOK	On Off Keying
PA	Power Amplifier
PCB	Printed Circuit Board
PLL	Phase-Locked Loop
POR	Power On Reset
RBW	Resolution BandWidth
RF	Radio Frequency
RSSI	Received Signal Strength Indicator
Rx	Receiver
SAW	Surface Acoustic Wave
SPI	Serial Peripheral Interface
SR	Shift Register
Stby	Standby
Tx	Transmitter
uC	Microcontroller
VCO	Voltage Controlled Oscillator
XO	Crystal Oscillator
XOR	eXclusive OR

This product datasheet contains a detailed description of the SX1232 performance and functionality. Please consult the Semtech website for the latest updates or errata.

1. General Description

The SX1232 is a single-chip integrated circuit ideally suited for today's high performance ISM band RF applications. The SX1232's advanced feature set includes a state-of-the-art packet engine and top level sequencer. In conjunction with a 64 byte FIFO, these automate the entire process of packet transmission, reception and acknowledgment without incurring the consumption penalty common to many transceivers that feature an on-chip MCU. Being easily configurable, it greatly simplifies system design and reduces external MCU workload to an absolute minimum. The high level of integration reduces the external BoM to passive decoupling and impedance matching components. It is intended for use as a high-performance, low-cost FSK and OOK RF transceiver for robust, frequency agile, half-duplex, bi-directional RF links. Where stable and constant RF performance is required over the full operating range of the device down to 1.8V the receiver and PA are fully regulated. For transmit intensive applications - a high efficiency PA can be selected to optimize the current consumption.

The SX1232 is intended for applications requiring high sensitivity and low receive current. Coupling the digital state machine with an RF front end capable of delivering a link budget of 143dB (-123dBm sensitivity in conjunction with +20dBm Pout). The SX1232 complies with both ETSI and FCC regulatory requirements and is available in a 5 x 5 mm QFN 24 lead package. The low-IF architecture of the SX1232 is well suited for low modulation index and narrow band operation.

1.1. Simplified Block Diagram

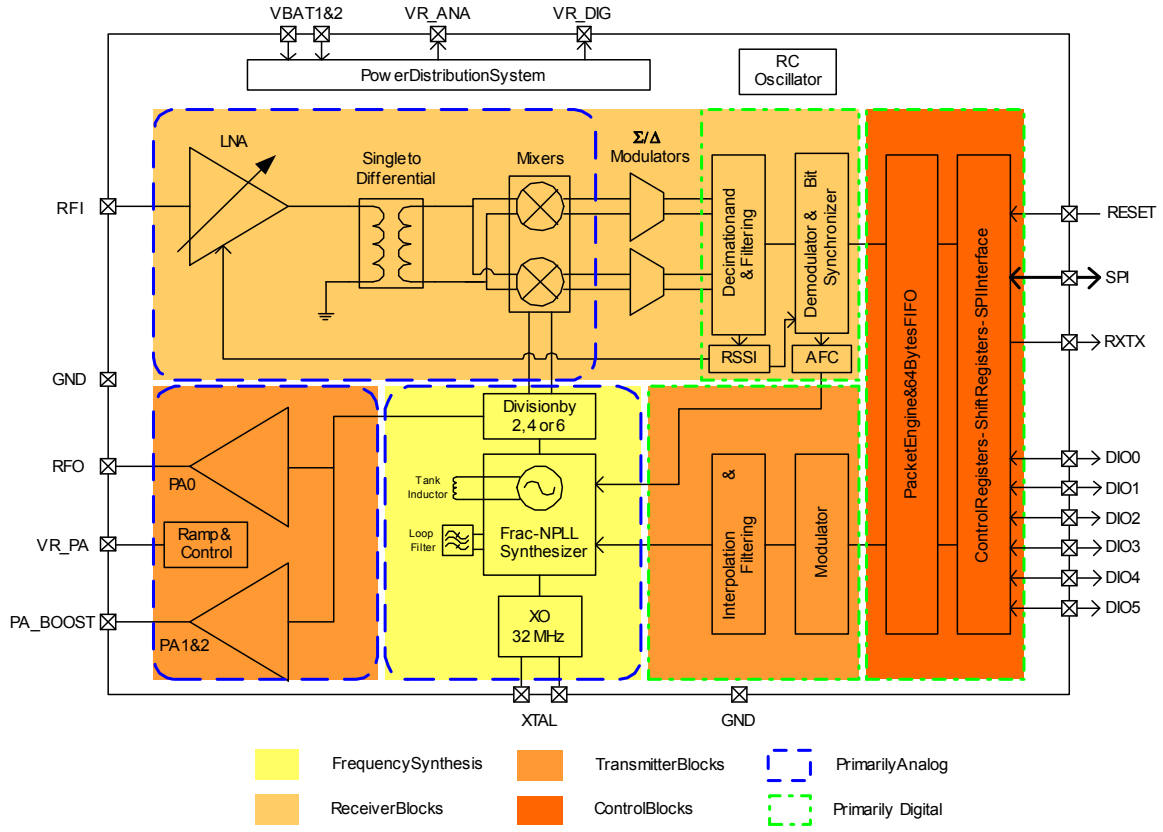

Figure 1. Block Diagram

1.2. Pin and Marking Diagram

The following diagram shows the pin arrangement of the QFN package, top view.

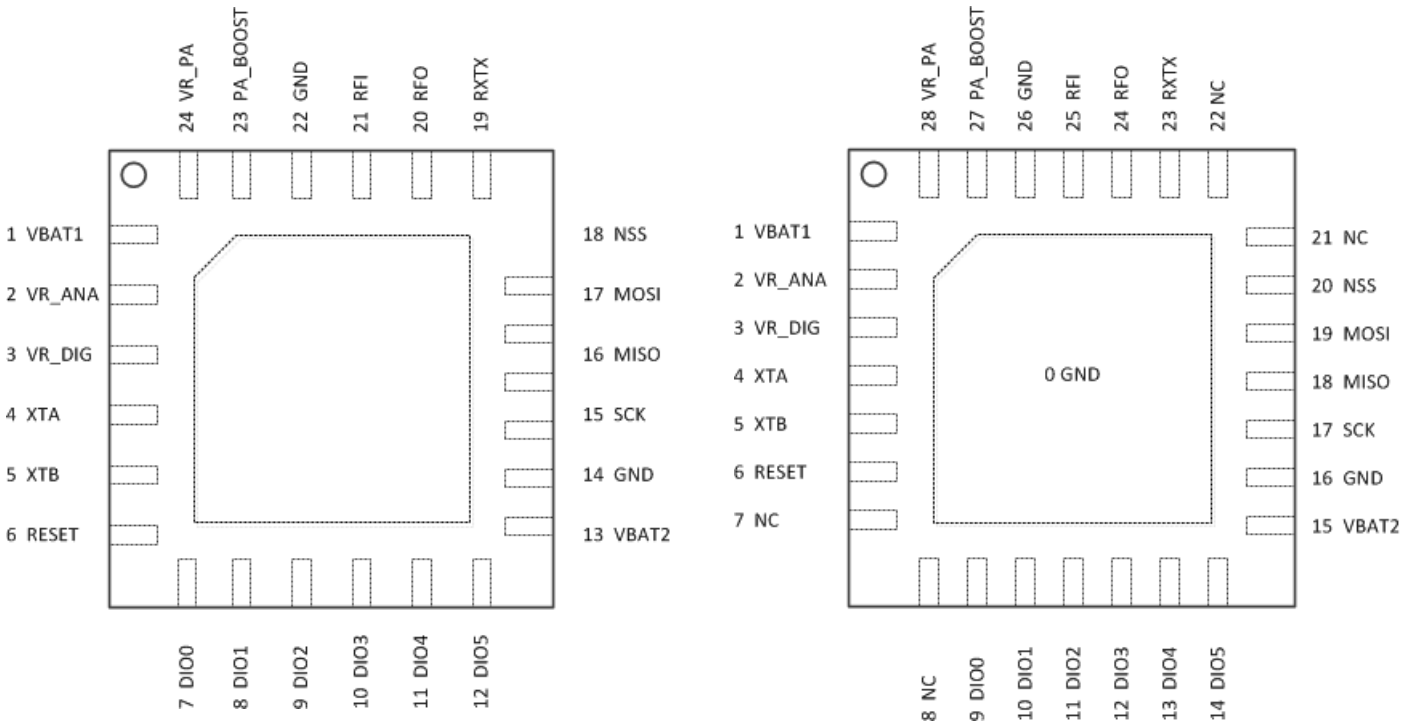

Figure 2. Pin Diagram SX1232 & SX1232B

Figure 3. Marking Diagram SX1232 & SX1232B

Notes nnnnnnn refers to the part number

vvww refers to the date code

xxxxxx refert to Semtech Lot No.

1.3. Pin Description

Table 1 SX1232 Pinouts

Number	Name	Type	Description
0	GROUND	-	Exposed ground pad
1	VBAT1	-	Supply voltage
2	VR_ANA	-	Regulated supply voltage for analogue circuitry
3	VR_DIG	-	Regulated supply voltage for digital blocks
4	XTA	I/O	XTAL connection or TCXO input
5	XTB	I/O	XTAL connection
6	RESET	I/O	Reset trigger input
7	DIO0	I/O	Digital I/O, software configured
8	DIO1/DCLK	I/O	Digital I/O, software configured
9	DIO2/DATA	I/O	Digital I/O, software configured
10	DIO3	I/O	Digital I/O, software configured
11	DIO4	I/O	Digital I/O, software configured
12	DIO5	I/O	Digital I/O, software configured
13	VBAT2	-	Supply voltage
14	GND	-	Ground
15	SCK	I	SPI Clock input
16	MISO	O	SPI Data output
17	MOSI	I	SPI Data input
18	NSS	I	SPI Chip select input
19	RXTX	O	Rx/Tx switch control: high in Tx
20	RFO	O	RF output
21	RFI	I	RF input
22	GND	O	Ground
23	PA_BOOST	O	Optional high-power PA output
24	VR_PA	O	Regulated supply for the PA

Table 2 SX1232B Pinouts

Number	Name	Type	Description
0	GROUND	-	Exposed ground pad
1	VBAT1	-	Supply voltage
2	VR_ANA	-	Regulated supply voltage for analogue circuitry
3	VR_DIG	-	Regulated supply voltage for digital blocks
4	XTA	I/O	XTAL connection or TCXO input
5	XTB	I/O	XTAL connection
6	RESET	I/O	Reset trigger input
7	Not Connected		
8	Not Connected		
9	DIO0	I/O	Digital I/O, software configured
10	DIO1/DCLK	I/O	Digital I/O, software configured
11	DIO2/DCLK	I/O	Digital I/O, software configured
12	DIO3	I/O	Digital I/O, software configured
13	DIO4	I/O	Digital I/O, software configured
14	DIO5	I/O	Digital I/O, software configured
15	VBAT2	-	Supply voltage
16	GND	-	Ground
17	SCK	I	SPI Clock input
18	MISO	O	SPI Data output
19	MOSI	I	SPI Data input
20	NSS	I	SPI Chip select input
21	Not Connected		
22	Not Connected		
23	RXTX	O	Rx/Tx switch control: high in Tx
24	RFO	O	RF output
25	RFI	I	RF input
26	GND	0	Ground
27	PA_BOOST	0	Optional high-power PA output
28	VR_PA	0	Regulated supply for the PA

2. Electrical Characteristics

2.1. ESD Notice

The SX1232 is a high performance radio frequency device. It satisfies:

- Class 2 of the JEDEC standard JESD22-A114-B (Human Body Model) on all pins.
- Class III of the JEDEC standard JESD22-C101C (Charged Device Model) on all pins

It should thus be handled with all the necessary ESD precautions to avoid any permanent damage.

2.2. Absolute Maximum Ratings

Stresses above the values listed below may cause permanent device failure. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Table 3 Absolute Maximum Ratings

Symbol	Description	Min	Max	Unit
VDDmr	Supply Voltage	-0.5	3.9	V
Tmr	Temperature	-55	+115	° C
Tj	Junction temperature	-	+125	° C
Pmr	RF Input Level	-	+10	dBm

Note Specific ratings apply to the +20dBm operation. Please refer to Section 3.4.7.

2.3. Operating Range

Table 4 Operating Range

Symbol	Description	Min	Max	Unit
VDDop	Supply voltage	1.8	3.7	V
Top	Operational temperature range	-40	+85	°C
Clop	Load capacitance on digital ports	-	25	pF
ML	RF Input Level	-	+10	dBm

Note A specific supply voltage range applies to the +20dBm operation. Please refer to Section 3.4.7.

2.4. Chip Specification

The tables below give the electrical specifications of the transceiver under the following conditions: Supply voltage VBAT1= VBAT2=VDD=3.3 V, temperature = 25 °C, *FXOSC* = 32 MHz, F_{RF} = 915 MHz, Pout = +13dBm, 2-level FSK modulation without pre-filtering, FDA = 5 kHz, Bit Rate = 4.8 kb/s and terminated in a matched 50 Ohm impedance, unless otherwise specified. Matching as per Figure 38.

Note Unless otherwise specified, the performance in the 868 MHz band is identical or better.

2.4.1. Power Consumption

Table 5 Power Consumption Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
IDDSL	Supply current in Sleep mode		-	0.1	1	uA
IDDIDLE	Supply current in Idle mode	RC oscillator enabled	-	1.2	-	uA
IDDST	Supply current in Standby mode	Crystal oscillator enabled	-	1.3	1.5	mA
IDDFS	Supply current in Synthesizer mode	FSRx	-	4.5	-	mA
IDDR	Supply current in Receive mode	*LnaBoost* = 00	-	9.3	-	mA
IDDT	Supply current in Transmit mode with impedance matching	RFOP = +20 dBm, on PA_BOOST RFOP = +17 dBm, on PA_BOOST RFOP = +13 dBm, on RFO pin RFOP = + 7 dBm, on RFO pin	- - - -	125 93 28 18	- - - -	mA mA mA mA

2.4.2. Frequency Synthesis

Table 6 Frequency Synthesizer Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
FR	Synthesizer frequency range	Programmable	862	-	1020	MHz
FXOSC	Crystal oscillator frequency	See section 7.1	-	32	-	MHz
TS_OSC	Crystal oscillator wake-up time	With crystal specified in section 7.1	-	250	-	us
TS_FS	Frequency synthesizer wake-up time to PllLock signal	From Standby mode	-	60	-	us
TS_HOP	Frequency synthesizer hop time at most 10 kHz away from the target frequency	200 kHz step 1 MHz step 5 MHz step 7 MHz step 12 MHz step 20 MHz step 25 MHz step	- - - - - - -	20 20 50 50 50 50 50	- - - - - - -	us us us us us us us
FSTEP	Frequency synthesizer step	FSTEP = FXOSC/2^{19}	-	61.0	-	Hz
FRC	RC Oscillator frequency	After calibration	-	62.5	-	kHz

BRF	Bit rate, FSK	Programmable values (1)	1.2	-	300	kbps
BRO	Bit rate, OOK	Programmable	1.2	-	32.768	kbps
BRA	Bit Rate Accuracy	ABS(wanted BR - available BR)	-	-	250	ppm
FDA	Frequency deviation, FSK (1)	Programmable FDA + BRF/2 =< 250 kHz	0.6	-	200	kHz

Note For Maximum Bit rate the maximum modulation index is 0.5

2.4.3. Receiver

All receiver tests are performed with RxBw = 10 kHz (Single Side Bandwidth) as programmed in *RegRxBw*, receiving a PN15 sequence. Sensitivities are reported for a 0.1% BER (with Bit Synchronizer enabled), unless otherwise specified. Blocking tests are performed with an unmodulated interferer. The wanted signal power for the Blocking Immunity, ACR, IIP2, IIP3 and AMR tests is set 3 dB above the receiver sensitivity level.

Table 7 Receiver Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RFS_F	Direct tie of RFI and RFO pins, as shown in Figure 38. FSK sensitivity, highest LNA gain.	FDA = 5 kHz, BR = 1.2 kb/s FDA = 5 kHz, BR = 4.8 kb/s FDA = 40 kHz, BR = 38.4 kb/s* FDA = 20 kHz, BR = 38.4 kb/s** FDA = 62.5 kHz, BR = 250 kb/s***	- - - - -	-119 -115 -105 -106 -92	- - - - -	dBm dBm dBm dBm dBm
	Split RF paths, as shown in Figure 39, LnaBoost is turned on, the RF switch insertion loss is not accounted for.	FDA = 5 kHz, BR = 1.2 kb/s FDA = 5 kHz, BR = 4.8 kb/s FDA = 40 kHz, BR = 38.4 kb/s* FDA = 20 kHz, BR = 38.4 kb/s** FDA = 62.5 kHz, BR = 250 kb/s***	- - - - -	-123 -119 -110 -110 -97	- - - - -	dBm dBm dBm dBm dBm
RFS_O	OOK sensitivity, highest LNA gain Conditions of Figure 38	BR = 4.8 kb/s BR = 32 kb/s	- -	-117 -108	- -	dBm dBm
CCR	Co-Channel Rejection		-	-8	-	dB
ACR	Adjacent Channel Rejection	FDA = 2 kHz, BR = 1.2kb/s, RxBw = 5.2kHz Offset = +/- 25 kHz	-	54	-	dB
		FDA = 5 kHz, BR=4.8kb/s Offset = +/- 25 kHz Offset = +/- 50 kHz	- -	50 50	- -	dB dB
BI	Blocking Immunity	Offset = +/- 1 MHz Offset = +/- 2 MHz Offset = +/- 10 MHz	- - -	73 78 87	- - -	dB dB dB
AMR	AM Rejection, AM modulated interferer with 100% modulation depth, fm = 1 kHz, square	Offset = +/- 1 MHz Offset = +/- 2 MHz Offset = +/- 10 MHz	- - -	73 78 87	- - -	dB dB dB

IIP2	2nd order Input Intercept Point Unwanted tones are 20 MHz above the LO	Highest LNA gain	-	+57	-	dBm
IIP3	3rd order Input Intercept point Unwanted tones are 1MHz and 1.995 MHz above the LO	Highest LNA gain G1 LNA gain G2, 4dB sensitivity hit	- -	-12 -8	- -	dBm dBm
BW_SSB	Single Side channel filter BW	Programmable	2.7	-	250	kHz
IMR	Image Rejection	Wanted signal 3dB over sens BER=0.1%	-	48	-	dB
IMA	Image Attenuation		-	56	-	dB
DR_RSSI	RSSI Dynamic Range	AGC enabled Min Max	- -	-127 0	- -	dBm dBm

* *RxBw = 83 kHz (Single Side Bandwidth)*

** *RxBw = 50 kHz (Single Side Bandwidth)*

*** *RxBw = 250 kHz (Single Side Bandwidth)*

2.4.4. Transmitter

Table 8 Transmitter Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RF_OP	RF output power in 50 ohms on RFO pin (High efficiency PA).	Programmable with steps Max Min	 +11 -	 +14 -1	 - -	 dBm dBm
ΔRF_OP_V	RF output power stability on RFO pin versus voltage supply.	VDD = 2.5 V to 3.3 V VDD = 1.8 V to 3.7 V	- -	3 8	- -	dB dB
RF_OPH	RF output power in 50 ohms, on PA_BOOST pin (Regulated PA).	Programmable with 1dB steps Max Min	- -	+17 +2	- -	dBm dBm
RF_OPH_MAX	Max RF output power, on PA_BOOST pin	High power mode	-	+20	-	dBm
ΔRF_OPH_V	RF output power stability on PA_BOOST pin versus voltage supply.	VDD = 2.4 V to 3.7 V	-	±1	-	dB
ΔRF_T	RF output power stability versus temperature on both RF pins.	From T = -40 °C to +85 °C	-	+/-1	-	dB

PHN	Transmitter Phase Noise	Low Consumption PLL, 915 MHz 50kHz Offset 400kHz Offset 1MHz Offset	 - - -	 -102 -114 -120	 - - -	dBc/Hz
		Low Phase Noise PLL, 915 MHz 50kHz Offset 400kHz Offset 1MHz Offset	 - - -	 -106 -117 -122	 - - -	dBc/Hz
ACP	Transmitter adjacent channel power (measured at 25 kHz off-set)	BT=1. Measurement conditions as defined by EN 300 220-1 V2.3.1	-	-	-37	dBm
TS_TR	Transmitter wake up time, to the first rising edge of DCLK	Frequency Synthesizer enabled, *PaRamp* = 10us, BR = 4.8 kb/s	-	120	-	us

2.4.5. Digital Specification

Conditions: Temp = 25°C, VDD = 3.3V, FXOSC = 32 MHz, unless otherwise specified.

Table 9 Digital Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
V_{IH}	Digital input level high		0.8	-	-	VDD
V_{IL}	Digital input level low		-	-	0.2	VDD
V_{OH}	Digital output level high	Imax = 1 mA	0.9	-	-	VDD
V_{OL}	Digital output level low	Imax = -1 mA	-	-	0.1	VDD
F_{SCK}	SCK frequency		-	-	10	MHz
t_{ch}	SCK high time		50	-	-	ns
t_{cl}	SCK low time		50	-	-	ns
t_{rise}	SCK rise time		-	5	-	ns
t_{fall}	SCK fall time		-	5	-	ns
t_{setup}	MOSI setup time	from MOSI change to SCK rising edge	30	-	-	ns
t_{hold}	MOSI hold time	from SCK rising edge to MOSI change	20	-	-	ns
t_{nsetup}	NSS setup time	from NSS falling edge to SCK rising edge	30	-	-	ns
t_{nhold}	NSS hold time	from SCK falling edge to NSS rising edge, normal mode	100	-	-	ns
t_{nhigh}	NSS high time between SPI accesses		20	-	-	ns
T_DATA	DATA hold and setup time		250	-	-	ns

3. Chip Description

This section describes in depth the architecture of the SX1232 low-power, highly integrated transceiver. The following figure shows a simplified block diagram of the SX1232.

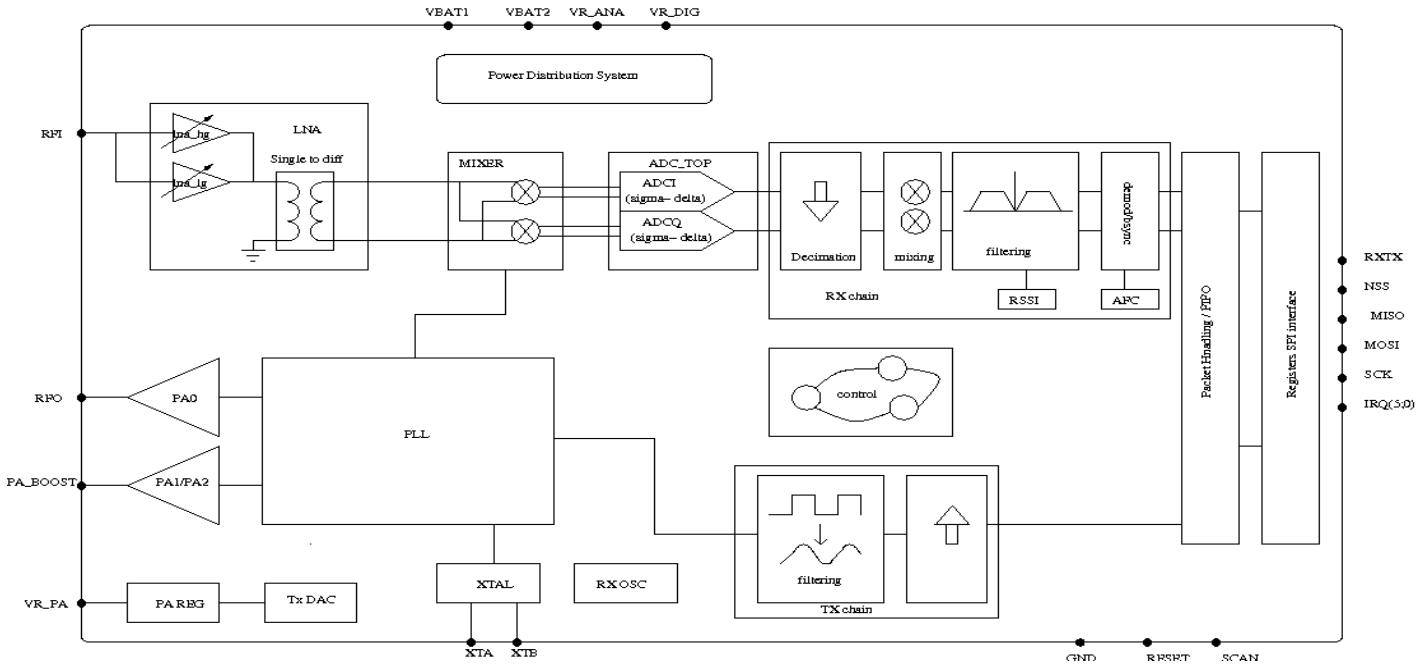

Figure 4. Simplified SX1232 Block Schematic Diagram

SX1232 is a half-duplex, low-IF transceiver. Here the received RF signal is first amplified by the LNA. The LNA input is single ended to minimise the external BoM and for ease of design. Following the LNA output, the conversion to differential is made to improve the second order linearity and harmonic rejection. The signal is then down-converted to in-phase (I) and quadrature (Q) components at the intermediate frequency (IF) by the mixer stage. A pair of sigma delta ADCs then perform data conversion, with all subsequent signal processing and demodulation performed in the digital domain. The digital state machine also controls the automatic frequency correction (AFC), received signal strength indicator (RSSI) and automatic gain control (AGC). It also features the higher-level packet and protocol level functionality of the top level sequencer.

In the receiver operating mode two states of functionality are defined. Upon initial transition to receiver operating mode the receiver is in the 'receiver-enabled' state. In this state the receiver awaits for either the user defined valid preamble or RSSI detection criterion to be fulfilled. Once met the receiver enters 'receiver-active' state. In this second state the received signal is processed by the packet engine and top level sequencer.

The frequency synthesiser generates the local oscillator (LO) frequency for both receiver and transmitter. The PLL is optimized for user-transparent low lock time and fast auto-calibrating operation. In transmission, frequency modulation is performed digitally within the PLL bandwidth. It also features optional pre-filtering of the bit stream to improve spectral purity.

SX1232 features a pair of RF power amplifiers. The first, connected to RFO, can deliver up to +14 dBm, is unregulated for high power efficiency and can be connected directly to the RF receiver input via a pair of passive components to form a single antenna port high efficiency transceiver. The second PA, connected to the PA_BOOST pin and can deliver up to +20 dBm via a dedicated matching network.

SX1232 also includes two timing references: an RC oscillator and a 32 MHz crystal oscillator.

All major parameters of the RF front end and digital state machine are fully configurable via an SPI interface which gives access to internal registers. This includes a mode auto sequencer that oversees the transition and calibration of the SX1232 between intermediate modes of operation in the fastest time possible.

3.1. Power Supply Strategy

The SX1232 employs an advanced power supply scheme, which provides stable operating characteristics over the full temperature and voltage range of operation. This includes the full output power of +17dBm which is maintained from 1.8 to 3.7 V.

The SX1232 can be powered from any low-noise voltage source via pins VBAT1 and VBAT2. Decoupling capacitors should be connected, as suggested in the reference design, on VR_PA, VR_DIG and VR_ANA pins to ensure a correct operation of the built-in voltage regulators.

3.2. Low Battery Detector

A low battery detector is also included allowing the generation of an interrupt signal in response to passing a programmable threshold adjustable through the register *RegLowBat*. The interrupt signal can be mapped to any of the DIO pins, by programming *RegDioMapping*.

3.3. Frequency Synthesis

3.3.1. Reference Oscillator

The crystal oscillator is the main timing reference of the SX1232. It is used as a reference for the frequency synthesizer and as a clock for the digital processing.

The XO startup time, TS_OSC, depends on the actual XTAL being connected on pins XTA and XTB. The SX1232 optimizes the startup time and automatically triggers the PLL when the XO signal is stable.

An external clock can be used to replace the crystal oscillator, for instance a tight tolerance TCXO. To do so, *TcxoInputOn* in *RegTcxo* should be set to 1, and the external clock has to be provided on XTA (pin 4). XTB (pin 5) should be left open.

The peak-peak amplitude of the input signal must never exceed 1.8 V. Please consult your TCXO supplier for an appropriate value of decoupling capacitor, C_D.

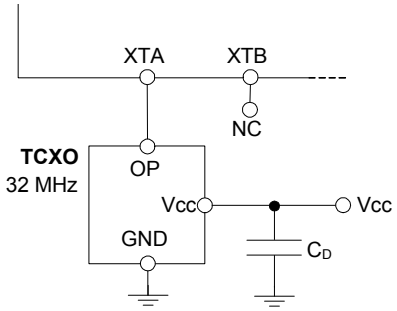

Figure 5. TCXO Connection

3.3.2. CLKOUT Output

The reference frequency, or a fraction of it, can be provided on DIO5 (pin 12) by modifying bits *ClkOut* in *RegDioMapping2*. Two typical applications of the CLKOUT output include:

- To provide a clock output for a companion processor, thus saving the cost of an additional oscillator. CLKOUT can be made available in any operation mode except Sleep mode and is automatically enabled at power on reset.
- To provide an oscillator reference output. Measurement of the CLKOUT signal enables simple software trimming of the initial crystal tolerance.

Note to minimize the current consumption of the SX1232, please ensure that the CLKOUT signal is disabled when not required.

3.3.3. PLL Architecture

The local oscillator of the SX1232 is derived from a fractional-N PLL that is referenced to the crystal oscillator circuit. Two PLLs are available for transmit mode operation - either low phase noise or low current consumption to maximize either transmit power consumption or transmit spectral purity. Both PLLs feature a programmable bandwidth setting where one of four discrete preset bandwidths may be accessed. For reference the relative performance of both low consumption and low phase noise PLL, for each programmable bandwidth setting, is shown in the following figure.

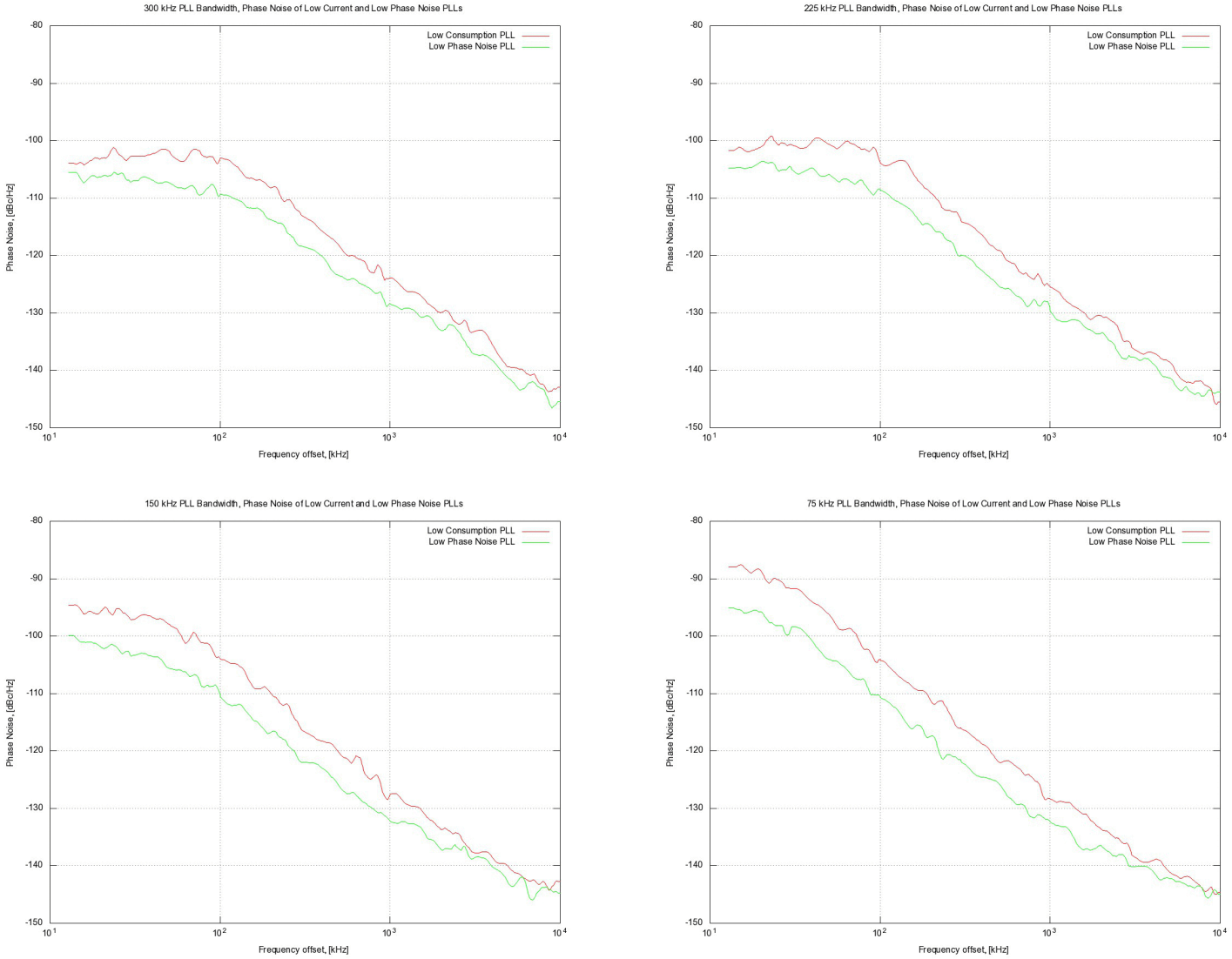

Figure 6. Typical Phase Noise Performances of the Low Consumption and Low Phase Noise PLLs.

Note in receive mode, only the low consumption PLL is available.

The SX1232 PLL embeds a 19-bit sigma-delta modulator and its frequency resolution, constant over the whole frequency range, and is given by:

$$F_{STEP} = \frac{F_{XOSC}}{2^{19}}$$

The carrier frequency is programmed through *RegFrf*, split across addresses 0x06 to 0x08:

$$F_{RF} = F_{STEP} \times Frf(23,0)$$

Note *The Frf setting is split across 3 bytes. A change in the center frequency will only be taken into account when the least significant byte FrfLsb in RegFrfLsb is written. This allows for more complex modulation schemes such as m-ary FSK, where frequency modulation is achieved by changing the programmed RF frequency.*

3.3.4. RC Oscillator

All timings in the low-power state of the Top Level Sequencer rely on the accuracy of the internal low-power RC oscillator. This oscillator is automatically calibrated at the device power-up, and it is a user-transparent process.

For applications enduring large temperature variations, and for which the power supply is never removed, RC calibration can be performed upon user request. *RcCalStart* in *RegOsc* triggers this calibration, and the flag *RcCalDone* will be set automatically when the calibration is over.

3.4. Transmitter Description

The transmitter of SX1232 comprises the frequency synthesizer, modulator and power amplifier blocks, together with the DC biasing and ramping functionality that is provided through the VR_PA block.

3.4.1. Architecture Description

The architecture of the RF front end is shown in the following diagram. Here we see that the unregulated PA0 is connected to the RFO pin features a single low power amplifier device. The PA_BOOST pin is connected to the internally regulated PA1 and PA2 circuits. Here PA2 is a high power amplifier that permits continuous operation up to +17 dBm and duty cycled operation up to +20 dBm. For full details of operation at +20 dBm please consult Section 3.4.7.

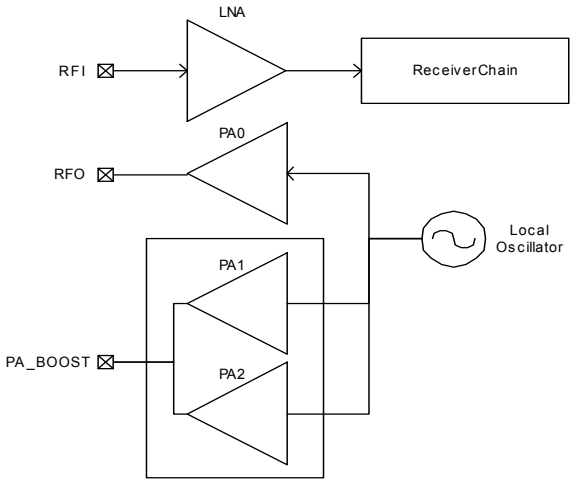

Figure 7. RF Front-end Architecture Shows the Internal PA Configuration.

3.4.2. Bit Rate Setting

The bitrate setting is referenced to the crystal oscillator and provides a precise means of setting the bit (or equivalently chip) rate of the radio. In continuous transmit mode (Section 3.2.2) the data stream to be transmitted can be input directly to the modulator via pin 9 (DIO2/DATA) in an asynchronous manner, unless Gaussian filtering is used, in which case the DCLK signal on pin 10 (DIO1/DCLK) is used to synchronize the data stream. See section 3.4.5 for details on the Gaussian filter.

In Packet mode or in Continuous mode with Gaussian filtering enabled, the Bit Rate (BR) is controlled by bits *Bitrate* in *RegBitrateMsb and RegBitrateLsb*

$$BitRate = \frac{FXOSC}{BitRate(15,0) + \frac{BitrateFrac}{16}}$$

*Note BitrateFrac bits have **no effect** (i.e may be considered equal to 0) **in OOK** modulation mode*

The quantity *BitrateFrac* is hence designed to allow very high precision (max. 250 ppm calculation error) for any bitrate in the programmable range. Table 10 below shows a range of standard bitrates and the accuracy to within which they may be reached.

Table 10 Bit Rate Examples

Type	BitRate (15:8)	BitRate (7:0)	(G)FSK (G)MSK	OOK	Actual BR (b/s)
Classical modem baud rates (multiples of 1.2 kbps)	0x68	0x2B	1.2 kbps	1.2 kbps	1200.015
	0x34	0x15	2.4 kbps	2.4 kbps	2400.060
	0x1A	0x0B	4.8 kbps	4.8 kbps	4799.760
	0x0D	0x05	9.6 kbps	9.6 kbps	9600.960
	0x06	0x83	19.2 kbps	19.2 kbps	19196.16
	0x03	0x41	38.4 kbps		38415.36
	0x01	0xA1	76.8 kbps		76738.60
	0x00	0xD0	153.6 kbps		153846.1
Classical modem baud rates (multiples of 0.9 kbps)	0x02	0x2C	57.6 kbps		57553.95
	0x01	0x16	115.2 kbps		115107.9
Round bit rates (multiples of 12.5, 25 and 50 kbps)	0x0A	0x00	12.5 kbps	12.5 kbps	12500.00
	0x05	0x00	25 kbps	25 kbps	25000.00
	0x80	0x00	50 kbps		50000.00
	0x01	0x40	100 kbps		100000.0
	0x00	0xD5	150 kbps		150234.7
	0x00	0xA0	200 kbps		200000.0
	0x00	0x80	250 kbps		250000.0
	0x00	0x6B	300 kbps		299065.4
Watch Xtal frequency	0x03	0xD1	32.768 kbps	32.768 kbps	32753.32

3.4.3. FSK Modulation

FSK modulation is performed inside the PLL bandwidth, by changing the fractional divider ratio in the feedback loop of the PLL. The large resolution of the sigma-delta modulator, allows for very narrow frequency deviation. The frequency deviation F_{DEV} is given by:

$$F_{DEV} = F_{STEP} \times Fdev(13,0)$$

To ensure a proper modulation, the following limit applies:

$$F_{DEV} + \frac{BR}{2} \leq (250)kHz$$

Note no constraint applies to the modulation index of the transmitter, but the frequency deviation must be set between 600 Hz and 200 kHz.

3.4.4. OOK Modulation

OOK modulation is applied by switching on and off the Power Amplifier. Digital control and smoothing are available to improve the transient power response of the OOK transmitter.

3.4.5. Modulation Shaping

Modulation shaping can be applied in both OOK and FSK modulation modes, to improve the narrowband response of the transmitter. Both shaping features are controlled with *PaRamp* bits in *RegPaRamp*.

- In FSK mode, a Gaussian filter with BT = 0.5 or 1 is used to filter the modulation stream, at the input of the sigma-delta modulator. If the Gaussian filter is enabled when the SX1232 is in Continuous mode, DCLK signal on pin 10 (DIO1/ DCLK) will trigger an interrupt on the uC each time a new bit has to be transmitted. Please refer to section 5.4.2 for details.
- When OOK modulation is used, the PA bias voltages are ramped up and down smoothly when the PA is turned on and off, to reduce spectral splatter.

Note the transmitter must be restarted if the ModulationShaping setting is changed, in order to recalibrate the built-in filter.

3.4.6. RF Power Amplifiers

Three power amplifier blocks are embedded in the SX1232. The first one herein referred to as PA0, can generate high efficiency RF power into a 50 ohm load. The RF power is programmable between -1dBm and +14dBm. PA0 is connected to pin RFO (pin 22).

PA1 and PA2 are both connected to pin PA_BOOST (pin 23). They can deliver up to +17 dBm in programmable step of 1dB to the antenna, a specific impedance matching / harmonic filtering design is required to ensure impedance transformation and regulatory compliance. The RF power is programmable between +2 dBm and +17 dBm. The high power mode allows to achieve fixed output power of +20dBm.

Table 11 Power Amplifier Mode Selection Truth Table

PaSelect	Mode	Power Range	Pout Formula
0	PA0 output on pin RFO	-1 to +14 dBm	-1 dBm + *OutputPower*
1	PA1 and PA2 combined on pin PA_BOOST	+2 to +17 dBm	+2 dBm + *OutputPower*
1	PA1+PA2 on PA_BOOST with high output power +20dBm settings (see 3.4.7)	+5 to +20 dBm	+5 dBm + *OutputPower*

Notes - For +20dBm restrictions of operation, please consult the following section

- To ensure correct operation at the highest power levels, please make sure to adjust the OcpTrim accordingly in RegOcp.

- If PA_BOOST pin is not used the pin can be left floating.